

U.S. Department of Commerce, Patent and Trademark	Atty. Docket No.	Application No.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	TNCR.178US2	10/791,026
(Use several sheets if necessary)	Applicant(s)	Conf. No.
	Wayne Chen et al.	1277
	Filing Date	Group
	March 1, 2004	2877

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>W</i>	1	4,449,818	May 22, 1984	Yamaguchi, et al.			
<i>W</i>	2	5,301,129	Apr., 1994	McKaughan et al.			
<i>W</i>	3	5,699,447	Dec., 1997	Alumot et al.			
<i>W</i>	4	5,808,735	Sep., 1998	Lee et al.			
<i>W</i>	5	5,864,394	Jan., 1999	Jordan, III et al.			
<i>W</i>	6	5,907,628	May, 1999	Yolles et al.			
<i>W</i>	7	5,991,699	Nov., 1999	Kulkarni et al.			
<i>W</i>	8	6,195,444	Feb., 2001	Simanovsky et al.			
<i>W</i>	9	6,201,601	Mar., 2001	Vaez-Iravani, et al.			
<i>W</i>	10	6,266,437	Jul., 2001	Eichel et al.			

U.S. Published Patent Application Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate

Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>W</i>	11	"Acoustic Scanners and Modulators," M. Gottlieb, Optical Scanning, ed. by Gerald F. Marshall, Dekker 1991, pp. 615-685.					
<i>W</i>	12	"CMP Applications for Sub-0.25.mu.m Process Technologies," D. Pramanik et al., presented at Electrochemical Society Proceedings: Chemical Mechanical Planarization in IC Device Manufacturing (2.sup.nd International Symposium), vol. 98-7, 1998.					
<i>W</i>	13	Integrated CMP Defect Monitoring Strategy," W. Chen et al., presented at The Electrochemical Society Proceedings: Chemical Mechanical Polishing in IC Device Manufacturing III, Editors: V.A. Arimoto et la., PV99-37, Honolulu, Oct. 1999.					

Examiner

Michael S. St.

Date Considered

11-15-04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.